AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claim 1 (canceled).

Claim 2 (currently amended): ~~The method to claim 1,~~ A method for producing an electronic part having a plurality of internal electrodes, said method comprising:

laminating a plurality of ceramic green sheets one on top of the other, at least some of the ceramic green sheets having conductive paste on a surface thereof such that the conductive paste is located between two adjacent ceramic green sheets, to form a laminated product; and

baking the laminated product to obtain the electronic part, the contraction ratio of the ceramic material forming the ceramic green sheet being greater than the contraction ratio of the conductive paste; wherein

the ceramic material and the conductive paste are selected to have contraction ratios such that a lateral edge of at least one of the internal electrodes has a portion which forms a wedge cross-sectional shape during baking; and

~~wherein a lateral edge of at least one of the internal electrodes has a wedge-like cross-sectional shape and~~ the length L of the wedge and the thickness t of the internal electrode at the base of the wedge satisfies the relationship $L > 2t$.

Claim 3 (currently amended): The method according to claim ~~1~~2, wherein the thickness of each of the internal electrodes is in ~~the~~ a range of about 3 μm to about 20 μm.

Claim 4 (currently amended): The method according to claim ~~1~~2, wherein the conductive paste has a low ratio of a binder to be scattered after baking and a high ratio of metal powders.

Claim 5 (previously presented): The method according to claim 4, wherein the conductive paste has about 2% to about 5% by weight of the binder with respect to 100% by weight of the metal powders.

Claim 6 (currently amended): The method according to claim ~~1~~2, wherein the conductive paste includes a high melting point metal.

Claim 7 (previously presented): The method according to claim 6, wherein the high melting point metal is at least one metal selected from the group consisting of Ni, Mo, and W.

Claim 8 (new): A method for producing an electronic part having a ceramic sintered body inside which a plurality of internal electrodes are arranged to overlap each other with a ceramic sintered body layer therebetween, said method comprising:

printing a conductive paste for forming an internal electrode on one main surface of a plurality of ceramic green sheets;

laminating the plurality of the ceramic green sheets with the conductive paste printed thereon;

laminating plain ceramic green sheets on and under the laminated plurality of ceramic green sheets with the conductive paste printed thereon to obtain a ceramic laminated body; and

baking the ceramic laminated body to obtain a ceramic sintered body; wherein

the plurality of ceramic green sheets and the conductive paste are selected such that the contraction ratio of the plurality of ceramic green sheets during baking is larger

than the contraction ratio of the conductive paste during baking such that during baking the ceramic green sheets will move toward the tip of the conductive paste which is burned to form a portion of the plurality of internal electrodes in a wedge cross-sectional shape.

Claim 9 (new): The method to claim 8, wherein a lateral edge of at least one of the internal electrodes has a wedge cross-sectional shape and the length L of the wedge and the thickness t of the internal electrode at the base of the wedge satisfies the relationship $L > 2t$.

Claim 10 (new): The method according to claim 8, wherein the thickness of each of the internal electrodes is in a range of about 3 μm to about 20 μm.

Claim 11 (new): The method according to claim 8, wherein the conductive paste has a low ratio of a binder to be scattered after baking and a high ratio of metal powders.

Claim 12 (new): The method according to claim 11, wherein the conductive paste has about 2% to about 5% by weight of the binder with respect to 100% by weight of the metal powders.

Claim 13 (new): The method according to claim 8, wherein the conductive paste includes a high melting point metal.

Claim 14 (new): The method according to claim 13, wherein the high melting point metal is at least one metal selected from the group consisting of Ni, Mo, and W.

Claim 15 (new): A method for producing an electronic part having a ceramic sintered body inside which a plurality of internal electrodes are arranged to overlap each other with a ceramic sintered body layer therebetween, said method comprising the steps of:

printing a conductive paste for forming an internal electrode on one main surface of a plurality of ceramic green sheets;

laminating and pressurizing the plurality of the ceramic green sheets with the conductive paste printed thereon;

laminating plain ceramic green sheets on and under the laminated plurality of ceramic green sheets with the conductive paste printed thereon to obtain a ceramic laminated body; and

baking the ceramic laminated body to obtain a ceramic sintered body; wherein

the ceramic laminated body has a low-density portion outside a tip of the plurality of internal electrodes during the step of laminating and pressurizing; and

the plurality of ceramic green sheets and the conductive paste are selected such that the contraction ratio of the plurality of ceramic green sheets during baking is larger than the contraction ratio of the conductive paste during baking such that during baking the ceramic green sheets will move toward the tip of the conductive paste which is burned to form a portion of the plurality of internal electrodes in a wedge cross-sectional shape.

Claim 16 (new): The method to claim 15, wherein a lateral edge of at least one of the internal electrodes has a wedge cross-sectional shape and the length L of the wedge and the thickness t of the internal electrode at the base of the wedge satisfies the relationship $L > 2t$.

Claim 17 (new): The method according to claim 15, wherein the thickness of each of th internal electrodes is in a range of about 3 μm to about 20 μm.

Claim 18 (new): The method according to claim 15, wherein the conductive paste has a low ratio of a binder to be scattered after baking and a high ratio of metal powders.

Claim 19 (new): The method according to claim 18, wherein the conductive paste has about 2% to about 5% by weight of the binder with respect to 100% by weight of the metal powders.

Claim 20 (new): The method according to claim 15, wherein the conductive paste includes a high melting point metal.

Claim 21 (new): The method according to claim 20, wherein the high melting point metal is at least one metal selected from the group consisting of Ni, Mo, and W.